

**On page 4 after the third paragraph, please insert the following heading:**

DETAILED DESCRIPTION OF THE INVENTION

**On page 11 after the first paragraph, please insert the following:**

It will be readily seen by one of ordinary skill in the art that the present invention fulfills all of the objects set forth above. After reading the foregoing specification, one of ordinary skill will be able to affect various changes, substitutions of equivalents and various other aspects of the invention as broadly disclosed herein. It is therefore intended that the protection granted hereon be limited only by the definition contained in the appended claims and equivalents thereof.

**ABSTRACT:**

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**ABSTRACT****~~PACKAGED ELECTRONIC COMPONENT FOR APPLICATIONS AT MILLIMETRIC FREQUENCIES~~**

The invention relates to millimetric packaged electronic components for applications at high frequencies greater than 45 GHz. According to the invention, to facilitate the design of a system including MMIC chips working at these frequencies, it is proposed to use packages containing one or more chips ~~[(22)]~~, these packages making it possible to work at these frequencies and including two types of port: a port ~~[(30)]~~ with transition by contactless electromagnetic coupling providing a connection with an antenna at the high working frequency  $F$  via a waveguide; and a port ~~[(40)]~~ with microstrip or coaxial line type transition enabling a connection at a subharmonic frequency  $F/N$  (preferably  $N = 6$  or  $4$  or, if necessary,  $3$ ) of the working frequency.

~~Application: radar systems.~~

~~Figure 1~~